



RELIABILITY REPORT
FOR
MAX3488ESA+
PLASTIC ENCAPSULATED DEVICES

November 17, 2010

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
Sokhom Chum
Quality Assurance
Reliability Engineer

Conclusion

The MAX3488ESA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I.Device Description	V.Quality Assurance Information
II.Manufacturing Information	VI.Reliability Evaluation
III.Packaging Information	IV.Die Information
.....Attachments	

I. Device Description

A. General

The MAX3483, MAX3485, MAX3486, MAX3488, MAX3490, and MAX3491 are 3.3V, low-power transceivers for RS-485 and RS-422 communication. Each part contains one driver and one receiver. The MAX3483 and MAX3488 feature slew-rate-limited drivers that minimize EMI and reduce reflections caused by improperly terminated cables, allowing error-free data transmission at data rates up to 250kbps. The partially slew-rate-limited MAX3486 transmits up to 2.5Mbps. The MAX3485, MAX3490, and MAX3491 transmit at up to 10Mbps. Drivers are short-circuit current limited and are protected against excessive power dissipation by thermal shutdown circuitry that places the driver outputs into a high-impedance state. The receiver input has a fail-safe feature that guarantees a logic-high output if both inputs are open circuit. The MAX3488, MAX3490, and MAX3491 feature full-duplex communication, while the MAX3483, MAX3485, and MAX3486 are designed for half-duplex communication.

II. Manufacturing Information

A. Description/Function:	3.3V Powered, 10Mbps and Slew-Rate Limited, True RS-485/RS-422 Transceivers
B. Process:	B3
C. Number of Device Transistors:	810
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	April 04, 1999

III. Packaging Information

A. Package Type:	8-pin SOIC (N)
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1901-0081
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	170°C/W
K. Single Layer Theta Jc:	40°C/W
L. Multi Layer Theta Ja:	128.4°C/W
M. Multi Layer Theta Jc:	36°C/W

IV. Die Information

A. Dimensions:	146 X 86 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 400 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 2.8 \times 10^{-9}$$
$$\lambda = 2.8 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B3 Process results in a FIT Rate of 0.51 @ 25C and 8.79 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (ESD Lot NGQDCO001A D/C 9617, Latchup lot NGQDEA6A9A D/C 0533)

The RS17-3 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX3488ESA+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	80	0	NGQCDQ001B, DC 9901
			80	0	NGQBDQ001B, DC 9901
			80	0	NGQEDQ001C, DC 9834
			80	0	NGQACA008B, DC 9647
			80	0	N180B4224DQ, DC N/A

Note 1: Life Test Data may represent plastic DIP qualification lots.